

SOT1823-1

FM2F, plastic, flange mount package; 2 terminals; 9.96 mm x 20.57 mm x 3.81 mm body

10 April 2019

Package information

1 Package summary

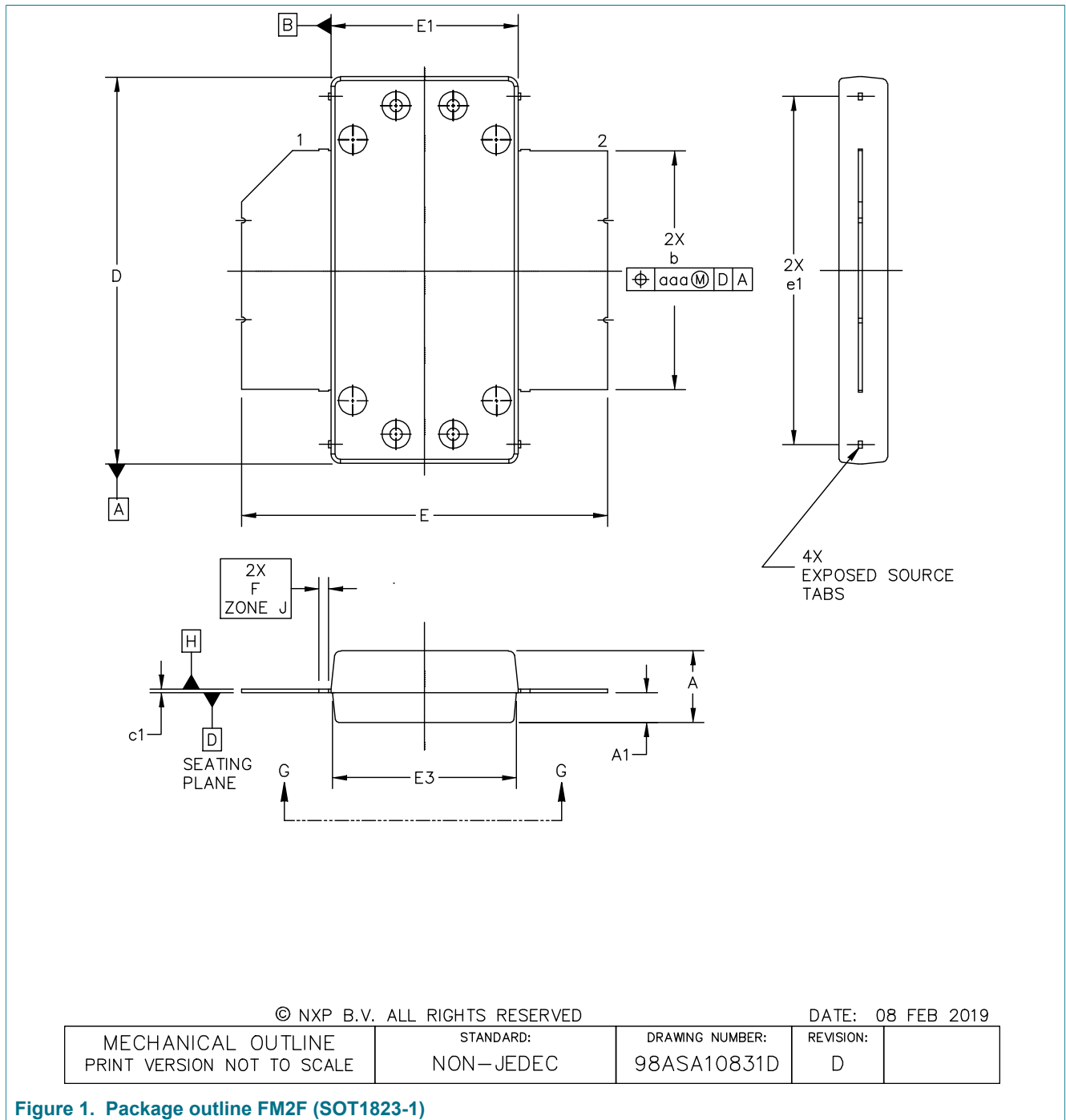
| | |
|---------------------------------------|---------------------------------|
| Terminal position code | D (double) |
| Package type descriptive code | FM2F |
| Package style descriptive code | DFM (double-ended flange mount) |
| Package body material type | P (plastic) |
| Mounting method type | F (flange mount) |
| Issue date | 08-02-2019 |
| Manufacturer package code | 98ASA10831 |

Table 1. Package summary

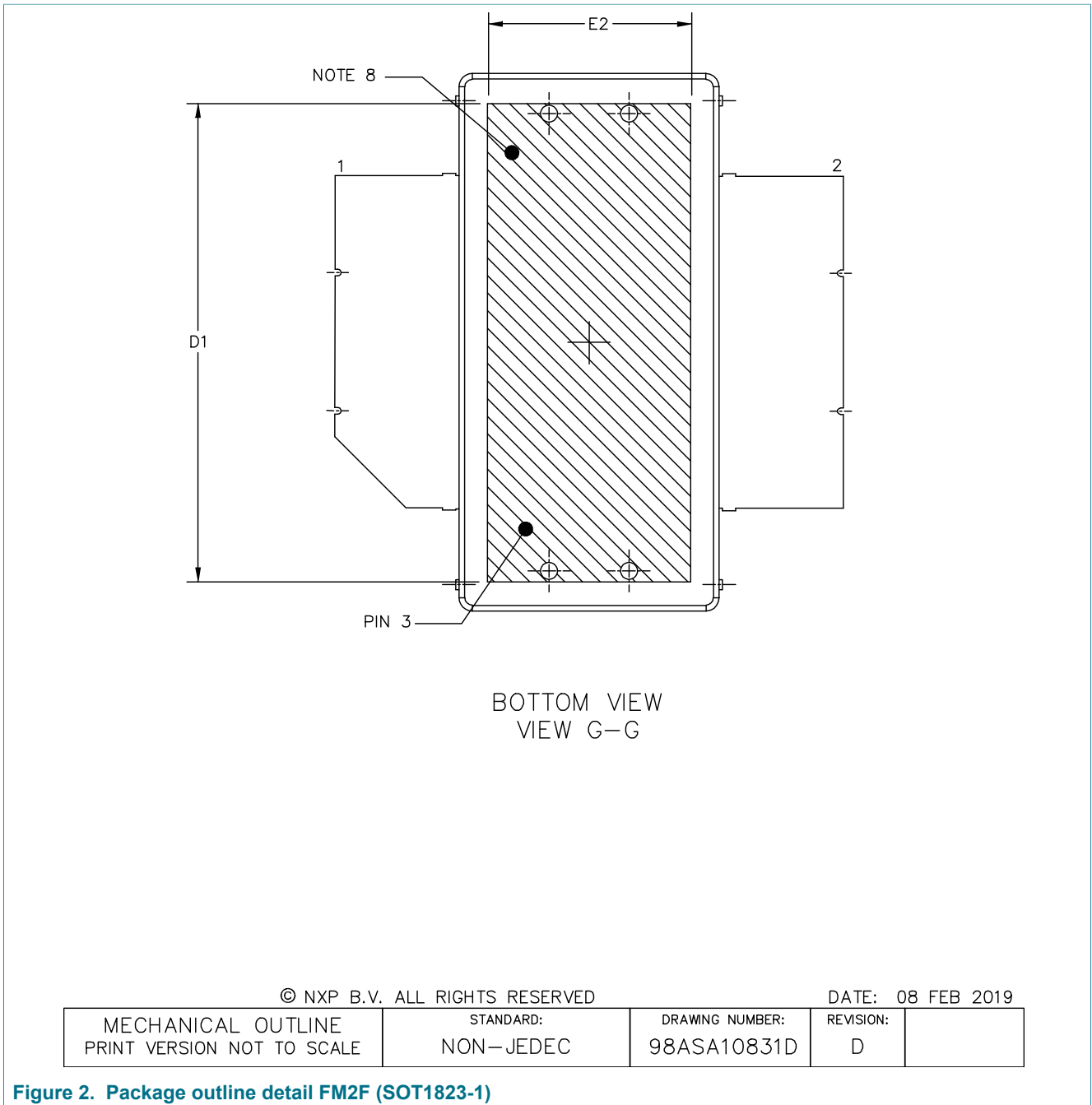
| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-------|-------|-------|------|
| package length | 20.52 | 20.57 | 20.62 | mm |
| package width | 9.91 | 9.96 | 10.01 | mm |
| package height | 3.76 | 3.81 | 3.86 | mm |
| actual quantity of termination | - | 2 | - | |



2 Package outline



FM2F, plastic, flange mount package; 2 terminals; 9.96 mm x 20.57 mm x 3.81 mm body



FM2F, plastic, flange mount package; 2 terminals; 9.96 mm x 20.57 mm x 3.81 mm body

NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) (PER SIDE). DIMENSIONS D AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A1 APPLIES WITHIN ZONE J ONLY
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D1 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.

| DIM | INCH | | MILLIMETER | | DIM | INCH | | MILLIMETER | |
|-----|----------|-------|------------|-------|-----|------|------|------------|-------|
| | MIN | MAX | MIN | MAX | | MIN | MAX | MIN | MAX |
| A | 0.148 | .152 | 3.76 | 3.86 | b | .497 | .503 | 12.62 | 12.78 |
| A1 | .059 | .065 | 1.50 | 1.65 | c1 | .007 | .011 | 0.18 | 0.28 |
| D | .808 | .812 | 20.52 | 20.62 | e1 | .721 | .729 | 18.31 | 18.52 |
| D1 | .720 | ----- | 18.29 | ----- | | | | | |
| E | .762 | .770 | 19.36 | 19.56 | aaa | .004 | | 0.10 | |
| E1 | .390 | .394 | 9.91 | 10.01 | | | | | |
| E2 | .306 | ----- | 7.77 | ----- | | | | | |
| E3 | .383 | .387 | 9.73 | 9.83 | | | | | |
| F | .025 BSC | | 0.635 BSC | | | | | | |

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DATE: 08 FEB 2019

| | | | | |
|--|------------------------|--------------------------------|----------------|--|
| MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE | STANDARD: NON-JEDEC | DRAWING NUMBER: 98ASA10831D | REVISION: D | |
|--|------------------------|--------------------------------|----------------|--|

Figure 3. Package outline note FM2F (SOT1823-1)

3 Legal information

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